

What is claimed is:

1. A stacked chip package comprising:
a board;
5 a first chip having bonding pads and stacked one atop the other on the board;
a first bonding wire connecting the bonding pad of the first chip with the board;
a second chip having bonding pads and a non-conductive adhesive layer and the
second chip being attached on the first chip;
a second bonding wire connecting the bonding pad of the second chip with the board;
10 a resin encapsulant sealing the first and second chips and the first and second bonding
wires;
solder balls formed on the rear side of the board and electrically connected with the
first and second chips, and
at least one heat transfer wire disposed between the first and second chips, each end of
15 the heat transfer wire being connected to the board.

2. The stacked chip package according to claim 1, wherein the bonding pads of
the first chip are arranged along opposite edges of the first chip and the heat transfer wires are
disposed parallel to the bonding pad arranging edge.

3. The stacked chip package according to claim 2, wherein the board has at least
one dummy board pad.

4. The stacked chip package according to claim 3, wherein the solder balls
25 include at least one dummy solder ball for heat dissipation and the dummy solder ball is
electrically connected with the dummy board pads.

5. The stacked chip package according to claim 4, wherein the dummy solder
ball includes at least one dummy solder ball for ground.

6. The stacked chip package according to claim 3, wherein the first chip further
includes a plurality of dummy bonding pads disposed along the opposite edges perpendicular
to the bonding pad arrangement and the heat transfer wires connect the dummy bonding pads
and the dummy board pads.

7. The stacked chip package according to claim 6, wherein the dummy bonding pad is provided on substantially the center portion of the first chip.

5 8. The stacked chip package according to claim 6, wherein the dummy bonding pad is arranged adjacent to the opposite edges and the heat transfer wire connects the dummy bonding pad formed at one edge and the dummy board pad formed at the edge opposite to the dummy bonding pad.

10 9. The stacked chip package according to any one of claims 1 through 8, wherein the second chip further has a plurality of dummy bonding pads and a second heat transfer wire, the dummy bonding pad being arranged along opposite edges of the second chip, the heat transfer wire being arranged parallel to the bonding pad arrangement of the first chip.